

<b>FORM PTO-1449</b>	Atty. Docket No.: 1100.1138101 (H16-17400)	Serial No.: 10/007,288
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Applicant: Wood et al.	
	Filing Date: December 3, 2001	Group Art: 1745

## U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
	3,577,037	5/1971	Di Pietro			
	3,973,146	8/1976	Arnold et al.			
	4,400,870	8/1983	Islam			
	4,122,479	10/1978	Sugawara et al.			
	4,369,458	1/1983	Thomas et al.			
	4,555,720	11/1985	Redhead			
	4,582,210	4/1986	Morimoto et al.			
	4,701,424	10/1987	Mikkor			
	4,766,316	8/1988	Jungkman			
	4,784,970	11/1988	Solomon			
	4,821,997	4/1989	Zdeblick			
	4,833,102	5/1989	Byrne et al.s			
	4,897,508	1/1990	Mahulikar et al.			
	5,006,711	4/1991	Hanashima et al.			
	5,021,663	1/1997	Hornbeck			
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	5,264,693	11/1993	Shimabukuro et al.			
	5,318,666	6/1994	Eklind et al.			
	5,366,587	11/1994	Ueda et al.			
	5,397,897	3/1995	Komatsu et al.			
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	5,521,123	5/1996	Komatsu et al.			
	5,528,452	6/1996	Ko			
	<del>5,581,631</del>	<del>12/1998</del>	<del>Borden et al.</del>			
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Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
	5,729,019	3/1998	Krafthefer et al.			
	<del>5,736,430</del>	<del>4/1998</del>	<del>Seefeldt et al.</del>			
	5,865,417	2/1999	Harris et al.			
	5,895,233	4/1999	Higashi et al.			
	6,036,872	3/2000	Wood et al.			
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Examiner Initial	Document No.	Date	Country	Translation Yes No
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	0453372	10/1991	EP	
	0736972	10/1996	EP	

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	Barth, Philip W., "Silicon Fusion Bonding for Fabrication of Sensors, Actuators and Microstructures", Sensors and Actuators, A21-A23, (1990) pages 919-926.
	Bauer D. et al., "Design and Fabrication of a Thermal Infrared Emitter", Sensors and Actuators A., vol. 55, No. 1, July 15, 1996, pages 57-63.
	Cabuz, C., et al., "Fabrication and packaging of a resonant infrared sensor integrated in silicon", Sensors and Actuators A, 43, May 1994, pages 92-99.
	Henmi, H., et al., "Vacuum packaging for microsensors by glass-silicon anodic bonding", Sensors and Actuators A, 43, May 1994, pages 243-248.
	Kniffen M.L. et al., "Packaging for Silicon Micromachined Accelerometers", International Journal of Microcircuits and Electronic Packaging, vol. 19, No. 1, January 1, 1996, pages 75-86.
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Mori T. et al., "Vacuum-encapsulated Thermistor bolometer Type Miniature Infrared Sensor".  
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Wolffenbuttel R.F., et al., "Low-temperature silicon wafer-to-wafer bonding using gold at eutectic  
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EXAMINER:

DATE CONSIDERED:

3/21/03

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citation if not in conformance and not considered. Include copy of this form with next communication to applicant.